



A system for characterization of DEPFET silicon pixel matrices and test beam results

S. Furletov
University of Bonn

On behalf of the DEPFET Collaboration

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Outline



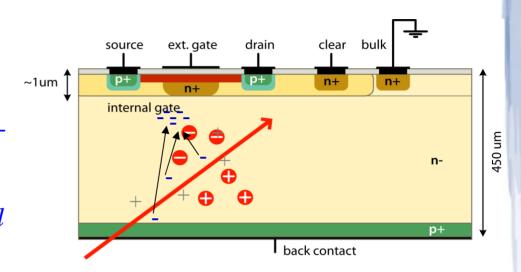
- Introduction to DEPFET readout
 - → The principle of DEPFET
 - → Readout electronics
 - → Data acquisition system (DAQ)
 - Online monitoring (DQM)
- Characterization of DEPFET matrices
 - Lab measurements: Laser and Am²⁴¹ source
 - →Test Beam Setup at CERN
- Data analysis software
- Test Beam results
- New developments
- Conclusion



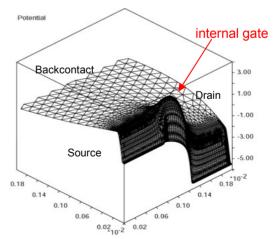
The Principle of DEPFET



- The DEPFET is an active pixel sensor which integrates a MOSFET into the high resistivity silicon substrate
 - in-pixel amplification
- Electrons are collected in "internal gate" potential minimum for electrons and modulate transistor current
- Transistor can be switched off by external GATE – charge collection still active!
- Charge from internal gate is removed via CLEAR contact
- Low readout capacitance reduces the noise
- Provides fast charge collection in fully depleted bulk
- more about DEPFET: www.depfet.org



Potential distribution



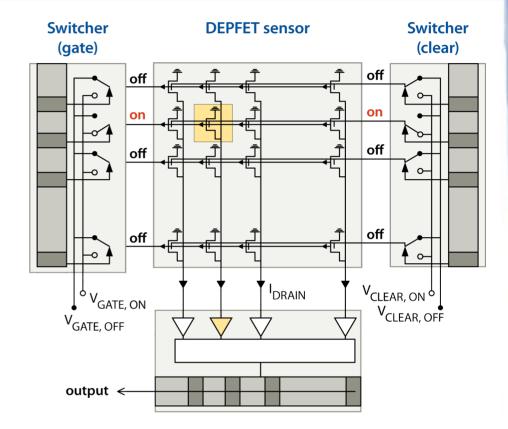
[ToSCA-Simulation]

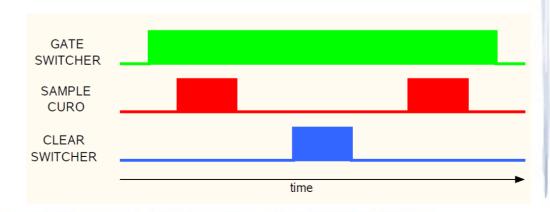


DEPFET readout sequence



- Sources of transistors are connected to common potential
- Gates are connected row-wise
- Drains are connected column-wise
- Readout chip CURO processes all columns in parallel
- The SWITCHER chip generates the steering signals for the rows GATE and CLEAR.
- DEPFET readout sequence :
 - → select row with external gate
 - → readout transistor current : I_sig + I_ped
 - → clear charge from internal gate
 - → again readout transistor current: I_ped
 - → subtract pedestal current
 - select next row



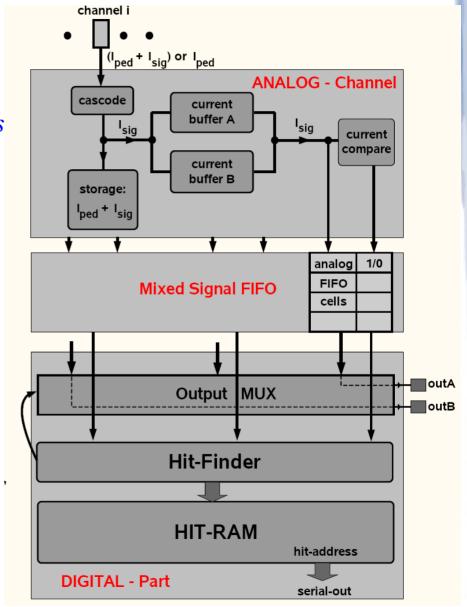




Readout chip CURO



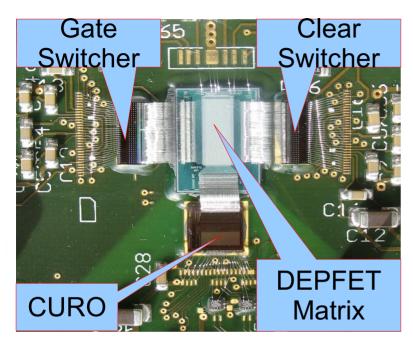
- CURO CUrent ReadOut consists of:
 - current memory cells
 - current comparator
- Current based readout with regulated cascodes
- CURO readout can work in 2 modes:
 - → readout all pixels row by row
 - zero suppression mode (not used)
- typical time scale for sample-clear-sample
 ~320 ns
- the general control of readout is managed by FPGA on readout board.
- the output of CURO is digitized by a 14 bit ADC and stored in SRAM for a subsequent readout.



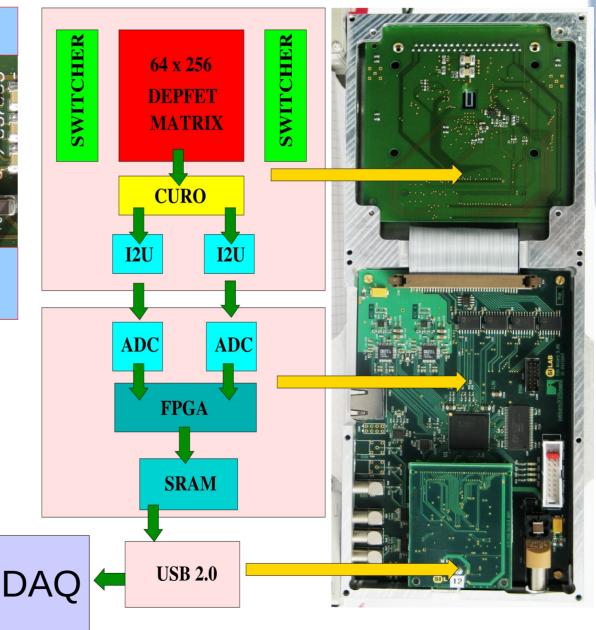


DEPFET readout board





- A second board (S3B) contains:
 - **→** FPGA
 - → ADCs
 - → buffer RAM
 - → USB2.0-PC interface.
- S3B board provides the read out rate up to 130 Hz
 - → Data rate about 4.2 MB/s per module (32 kB / frame)

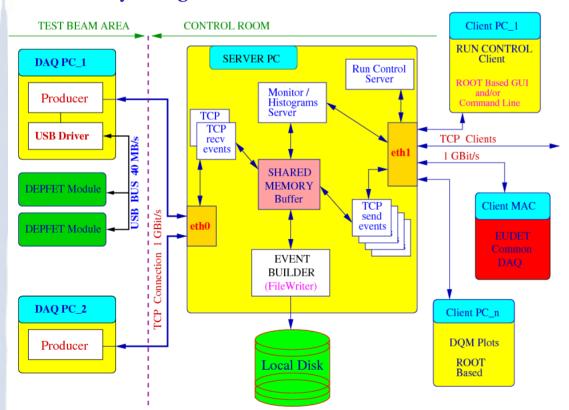




Network DAQ System



- DAQ is based on Linux network distributed client/server architecture which allows:
 - share resources and tasks
 - easy scale the system
 - → remote control and monitoring
 - easy integration of other detectors



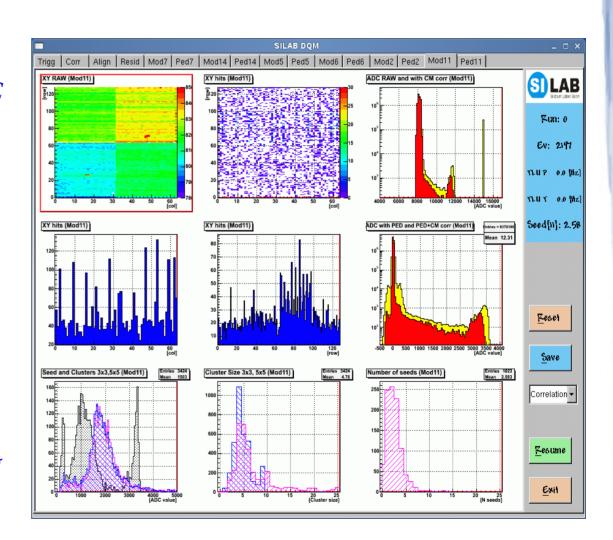
- DAQ uses USB 2.0 for data transfer from DEPFET R/O board to PC and TCP/IP to send data to Event Builder.
- The DAQ components are:
 - → a LINUX based USB driver for the DEPFET DAQ board
 - → a USB readout client transferring data to an event builder via network;
 - an Event Builder assembling complete events and storing in a shared memory buffer;
 - → an event server send complete event to consumers (file writer, DQM, upper level DAQ, histogram server);
 - online Data Quality Monitoring (DQM) package based on ROOT.
 - Run control server can accept commands from different clients:
 - → Command line interface via Telnet
 - → TCL/TK or Root GUI
 - Another program with TCP connection to Run Control



Data Quality Monitor



- Network Data Acquisition system allows to run powerful Data Quality Monitor on dedicated PC in real time
- DQM is based on ROOT:
 - includes various data access methods: file, shared memory, network
 - online data processing –
 pedestal and common mode
 calculation, cluster
 reconstruction and simple
 tracking.
 - can also act as network histogram server
- advanced DQM functionality allows to find most of DAQ and DEPFET matrix problems during the run
- WEB interface for remote DQM





Power Supplies

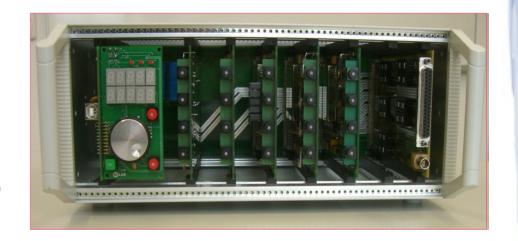


- Up to 20 supply voltages are needed for operating a DEPFET system
- Special multi channel power supplies have been built to conveniently provide all voltages
- Computer controlled power supplies houses in small (15" case):
 - → one supply per DEPFET module
 - → safe power on sequence, (μC controlled)
 - easy voltage and current monitoring
 - → remote access to voltage settings:
 - DUT voltage scans

Operation voltages of a DEPFET matrix with respect to source (0V)

	Collection	Read	Clear		
V_{Gate}^*	3V	-2V	-2V		
V_{Clear}^*	2V	2V	15V		
V_{Drain}^{**}	-5V				
$V_{ClearGate}$	-2V				
V_{Bulk}	10V				
V_{Back}^{***}	-10V50V				

- * * control lines (transferred via Switcher)
- ** provided by readout input stage
- *** depending on final detector thickness and contact mode



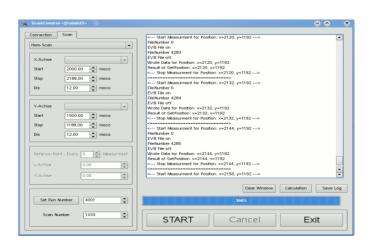




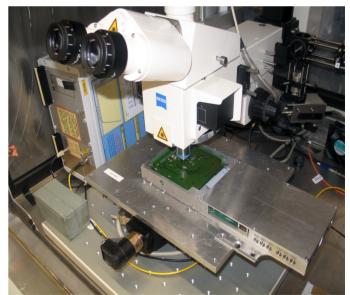
Laser Measurements in LAB



- Laser tests are done in order to study inhomogeneity of the matrix response using laser systems with different wavelengths:
 - → 682 nm, 810 nm and 1055 nm.
- The laser spot is focused on the matrix backplane with spot sizes which vary from 2.5 µm to 5 µm.
- The DEPFET module is mounted on a motor-controlled xy-stage with steps of the order of 1 μm, allowing a full automatic scan of the matrix surface
- Scanning software controls a motor table, laser and a data acquisition





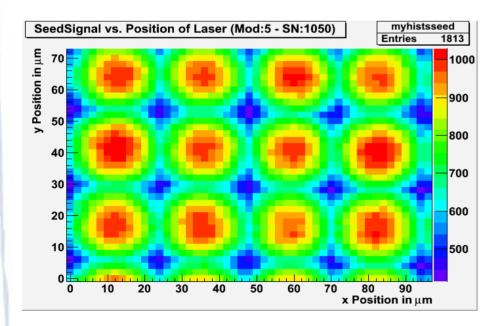




Laser measurements

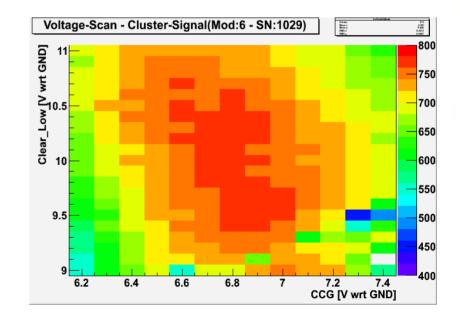


- In-pixel structure of DEPFET can be resolved
- Pixel size of a DEPFET sensor:
 - **→** 24x24 µm
- Figure shows an example of the variations of the pixel seed signal across the matrix.
- Charge is shared in area of 3x3 pixels
 - → In seed pixel we have about half of total charge



Step size: 2µm

- Response of DEPFET sensor is mainly depending on three voltages:
 - Clear High
 - Clear Low
 - → Common Clear Gare (CCG)
- Automatic Scan of these voltages is used to define optimal parameters of the module.





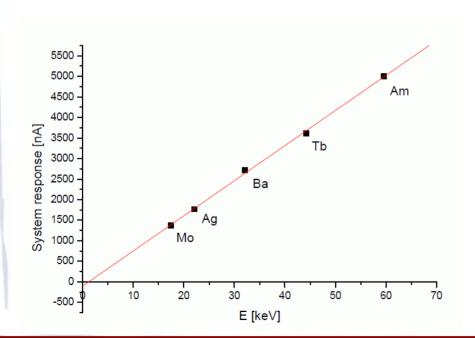
Tests with radioactive sources



• Internal amplification of DEPFET - G_q defined as:

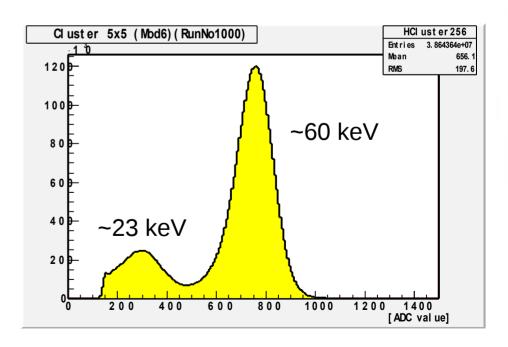
$$\rightarrow$$
 $G_q = \Delta I_d / e^-$

- For an absolute measurement of the gain G_q : spectra of radioactive sources are measured
- Measurements are usually performed using sources: ⁵⁵ Fe, ¹⁰⁹ Cd, ¹³³ Ba and ²⁴¹ Am



- Prototypes with the standard channel geometry have a G of about 400 pA/e
- DEPFETs with a scaled channel geometry show even better results $G_q = 650 \text{ pA/e}^-$.

Energy spectrum of 241 Am

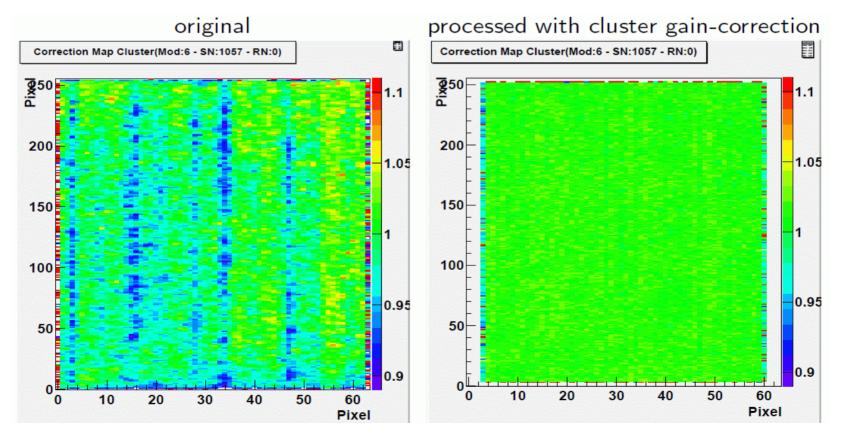




Matrix homogeneity measurements



- The uniformity of the response over the DEPFET sensor has been measured.
- A spread of 5 % is observed when comparing the response of the over 16000 pixels of a sensor.
- This effect does not affect the spatial resolution significantly.
- Also it is possible to correct the difference in pixels gain.





Test beam infrastructure



- Beam tests of DEPFET prototypes form an important complement to the laboratory test procedures
- Their main aim is to characterize the response of DEPFET prototypes to minimum ionizing particles, and to establish the spatial resolution of the devices.
- Since 2005, DEPFET prototypes have been submitted to multiple beam tests in a 6 GeV electron beams at DESY, 24 GeV proton beams at the CERN PS and 120 GeV pion beams at the CERN SPS.
- Sophisticated beam test infrastructure has been developed:
 - → Mechanics:
 - support table for installation of DEPFET telescope system
 - X-Y motor stages with remote control, for alignment of DEPFET modules
 - → Trigger includes:
 - scintillation counters in coincidence
 - Trigger Logic Unit (TLU) for synchronization readout system
 - → Readout electronics
 - DEPFET matrix power supply
 - → Data Acquisition system (DAQ)
 - Including PCs, network hardware and
 - → Data quality monitor (DQM)

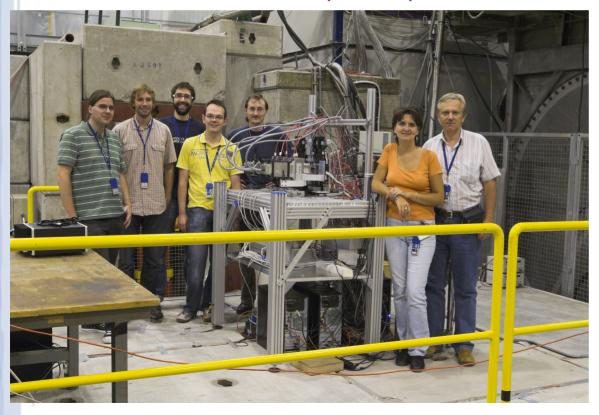


DEPFET Test Beam

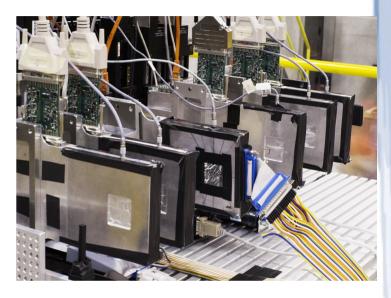


- Jul-Aug 2008, August 2009
- CERN SPS H6 beam line
- 120 GeV pions

Test beam crew also important part of tests



DEPFET Telescope



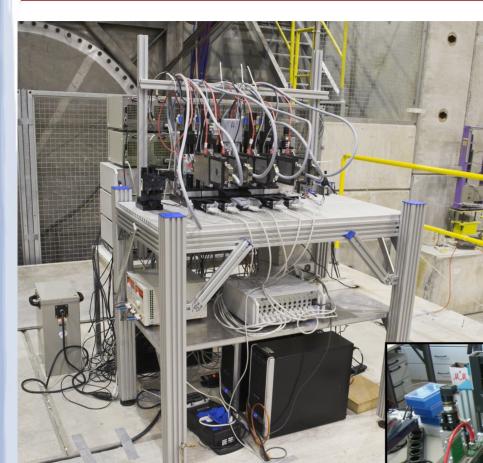
EUDET Telescope + DEPFET as DUT





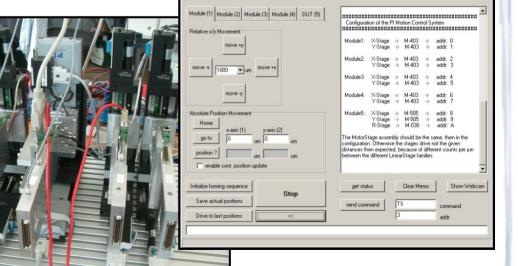
Mechanics





- Telescope positioning system:
 - → Mechanics
 - moving range: 100/150mm, 90°rotation for DUT
 - positioning accuracy $15\mu m / 2\mu m$ (DUT)
 - **→** Controllers
 - Positioning software

mounting table (1600x625x1050 mm)





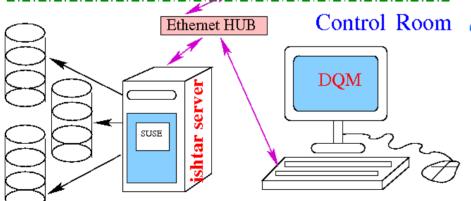
Test Beam setup for CERN 2009





Beam Area

- → 2 readout PC with 3 DEPFET modules per PC, connected via USB2.0 in the test beam area in distance of max. 4 meters from the modules.
- → Windows PC to control 6 X-Y motor stages, with USB2.0 connection to controller.
- → Trigger Logic Unit (TLU) connected to one of readout PC via USB2.0
- → all PC are connected to 1GB ethernet HUB



– USB –

SUSE

Ethernet HUB

• Control Room:

- → one DAQ server rack mounted server PC: Intel S5000, 8 CPU, 4GB memory, hot swap SATA RAID with 3 TByte disk space total 6 disks.
- → working PC : Run Control, DQM, etc....
- → all PC also connected to local ethernet HUB
- → both HUBs are connected by ethernet cable, from test beam area to control room

SUSE



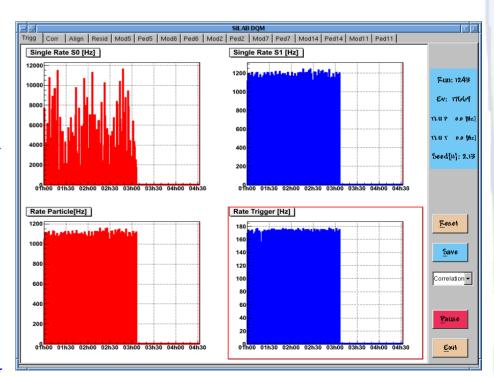
Trigger and Events Rate





- A dedicated Trigger Logic Unit (TLU) accepts signals from the scintillators or external trigger and generates a signal to trigger the system.
- Each trigger carries a unique number and time stamp.

- H6 line with 120 GeV pions
- Coincidence rate of 2 scintillators is about 1000 Hz
- DAQ with slow readout sequence (readout full matrix 64x128) accepts 180-220 Hz depending on number of readout PCs.
- Data volume rate for 6 modules is about 20 GB / hour
- One disk of 500GB is filled in 1-2 days
- Hot swapping RAID system allows to change the disks without stopping taking data



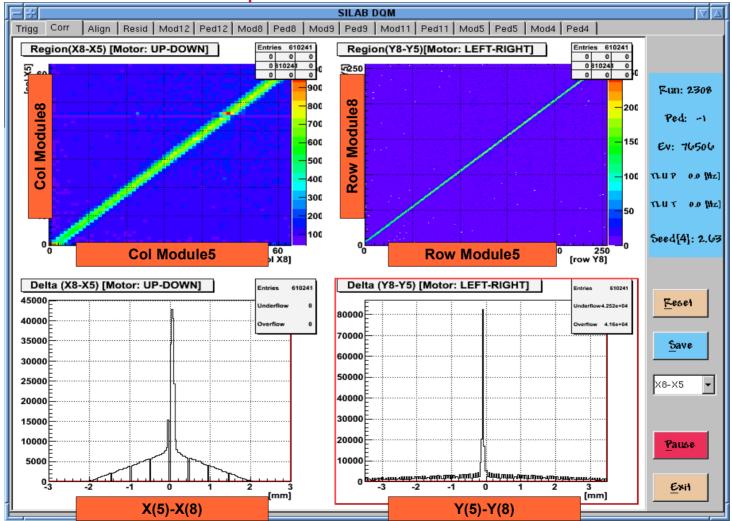


Initial alignment of TB setup



- Online Monitor also is used for alignment of all 6 modules on the beam line:
 - → 6 sensors with size of 2x3 mm and distance between modules about 20 cm

Correlation plots for two modules: Mod8 & Mod5





Analysis



- Data analysis has been carried out and cross-checked by several groups, each using different tools:
 - → Framework (ILC/EUTelescope vs. ROOT)
 - → Alignment (Millepede vs. alignment)
- The analysis groups collectively cover a wide range of specialized analysis tasks (from charge collection homogeneity analyses to studies of response variations across detector matrices to calculation of detector resolutions
- Detector (spatial) resolutions (Prague)
 - → calculated from fit residuals by "subtracting" multiple scattering contribution using the statistical models of particle track and multiple scattering.
 - Useful tool to study and optimize detector properties (hit reconstruction, homogeneity of response etc.)
- Simulation studies and digitization:
 - → For validation of analysis
 - → For studies of detector designs for HEP experiments (Belle II, ILC)



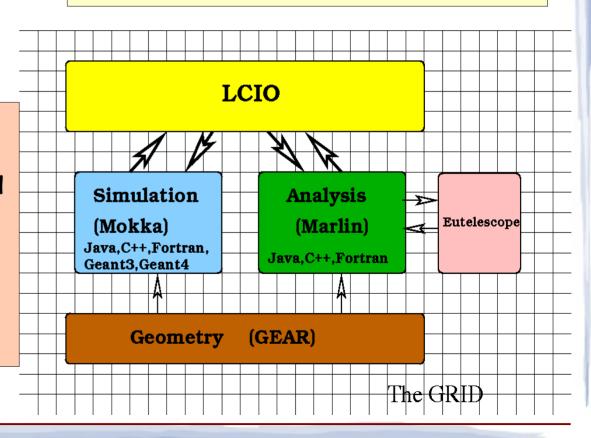
ILC data analysis software



- Data analysis is based on ILC framework software for tracking and alignment with modification for DEPFET specifics mainly in part
 - of cluster reconstruction
 - common mode correction.

- LCIO (LiniarCollider I/O): persistency framework and data model
- MARLIN: C++ application framework
- · GEAR: geometry description
- · RAIDA: interface to ROOT

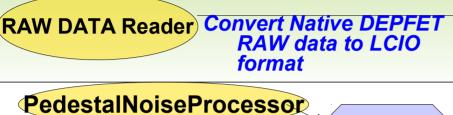
- Advantages:
- use standard analysis tools and reconstruction software
- → space for own development
- integrate with GRID for data
 management and processing

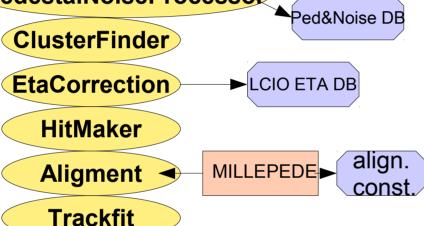




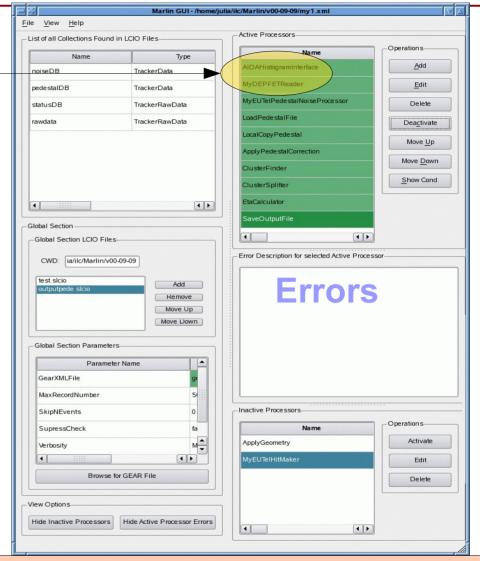
ILC/EUTelescope software







- LCIO (LiniarCollider I/O):
 persistency framework and data model
 that has been adopted as a standard
 by the international ILC community.
- •MARLIN:C++ application framework
- •GEAR: geometry description
- ◆RAIDA: interface to ROOT
- ·Eutelescope: applications for TestBeam



Advantages of the ILC software:

- →standard analysis tools and reconstruction software
- ⇒space for own development
- →integrated with GRID for data management and processing

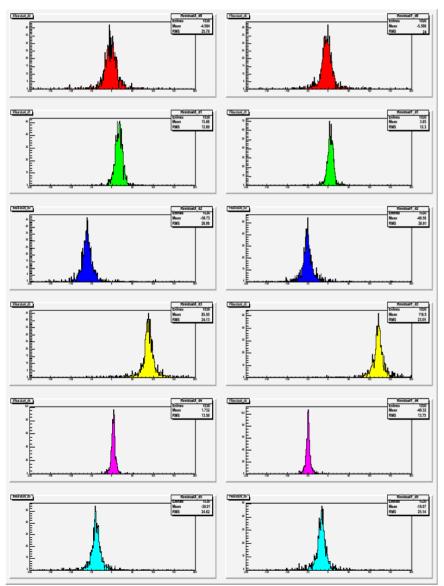


Milepede II alignment



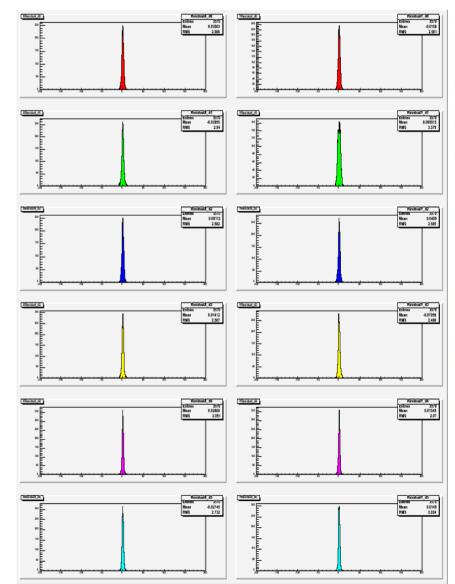
Before alignment

(track-hitX) (track-hitY)



After alignment

(track -hitX) (track-hitY)



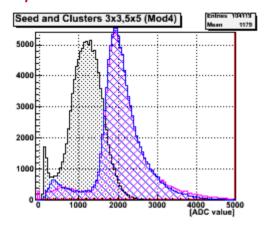


Cluster signal and noise

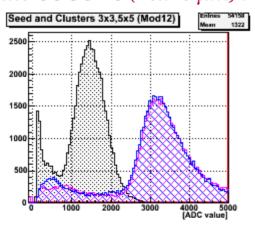


• The most probable signal ranges from 1600 to over 3000 ADU in different sensor designs.

Telescope Module COCGLB: S/N ~130

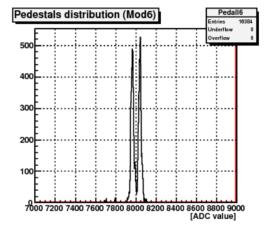


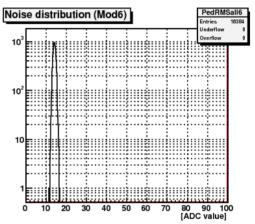
Module COCG VS (20x20 µm): S/N ~220

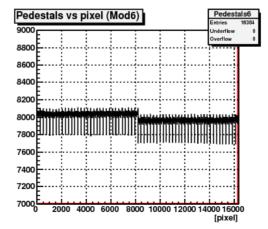


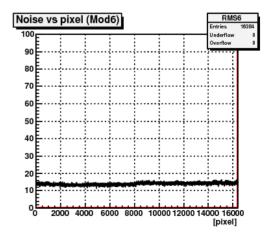
- The noise level in these devices is approximately 13 to 14 ADU.
 - → signal-to-noise ratio of well over 100.
 - → S/N for COCG VS over 200

Pedestal and noise distributions











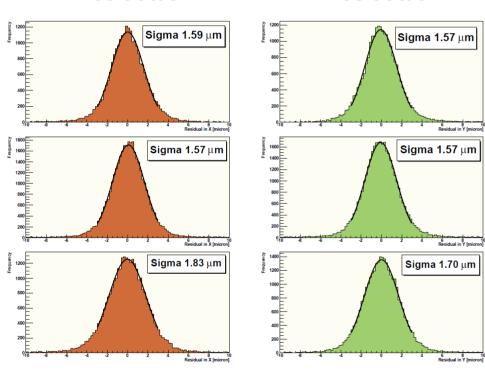
Preliminary TB 2009 analysis

Residuals Y

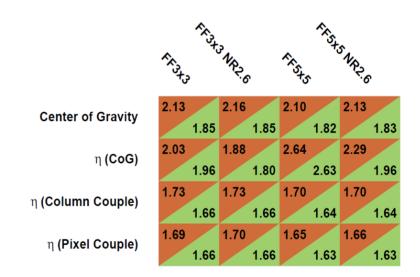


Analysis of the DEPFET data at University of Göttingen, using ILC/EUDET software

Residuals X



Residuals in \times and y of H3.0.04, H3.0.07 and H3.0.01. Telescope and DUT hits reconstructed with eta px couple algorithm.



The matrix chart displays the residuals for x (red) and y (green) in dependence of the clustering procedure and the hit reconstruction algorithm in μm .

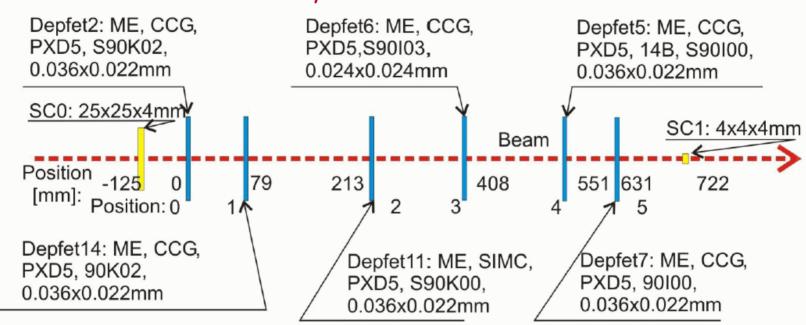
FF = Full Frame; NR2.6 = Noise Reject at 2.6 Sigma



Final TB 2008 resolution



Geometry of the 2008 beam test.



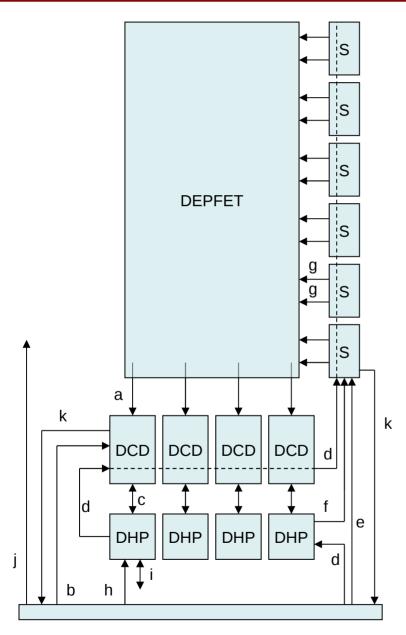
Final residuals and resolutions from Prague analysis

I mai restaudis and resolutions from rraque analysis						
	Module 0	Module 1	Module 2	Module 3	Module 4	Module 5
	CCGME-	CCGME-	SIMCME-	CCGME-	CCGME-	CCGME-
Y resolution $[\mu m]$	-S90K02	-90K02	-S90K00	-S90I03	-S90I00	-90I00
	$32x24 \mu m$	$32\mathrm{x}24~\mu\mathrm{m}$	$32\mathrm{x}24~\mu\mathrm{m}$	$24x24 \mu m$	$32x24 \mu m$	$32\mathrm{x}24~\mu\mathrm{m}$
X residual $[\mu m]$	2.9	2.2	2.3	2.0	3.1	3.4
Y residual $[\mu m]$	2.3	1.7	1.7	1.7	2.2	2.6
X resolution $[\mu m]$	2.1	1.6	1.9	1.3	2.6	2.4
Y resolution $[\mu m]$	1.5	1.3	1.2	1.2	1.8	1.7



New Readout of DEPFET





- a A(0:255)
- b analog AVDD, AGND, AmpLow, Refln (+4xrefCurr) digital DVDD, DGND
- c DCD->DHP DO(0:63), RefOutDHP->DCD DI(0:15)DCD->DHP CLK, SYNC_RES, STRSYNCHR(0:1)
- d JTAG5x
- e HV AHI, ALO, BHI, BLO, SUB, Ref?
 LV VDDD3.3, GNDD, VDDJTAG1.8
- f CLK, SERIN, SEROUT STRGATE, STRCLR
- g CLR(0:31), GATE(0:31)
- h VDDDC_DHP, GNDD_DHP, VDDGB_DHP, VDD1.8_DHP,
- i IO DHP
- j S, CG, PC, GU, HV
- k Monitor_DCD, MonA_SW, MonB_SW



Conclusion



- A system for characterization of DEPFET matrices includes:
 - → Laser and radioactive sources setups at Laboratory
 - → Test Beam setups (CERN, DESY)
 - Standalone DEPFET telescope
 - Integration with EUDET telescope on the hardware and software level
- Data acquisition system is running stable and has shown good performance
 - → Operated 6 layers DEPFET telescope (trigger rate ~100 Hz, data rate ~20 GB/hour)
 - → Collected ~ 20 millions events for analysis (~4TB raw data)
 - → Flexibility: DEPFET DAQ has been successfully integrated to EUDET readout system
- Analysis Software
 - → Several analysis tools from a different groups are available to cross check the results.
 - → ILC/EUTelescope software is used as default for data analysis.
- The spatial resolution in TB2008 for matrix with $24 \times 24 \mu m^2$ pixels is found to be:

$$\sigma_x = 1.3 \pm 0.2 \ \mu m$$
, $\sigma_y = 1.2 \pm 0.1 \ \mu m$

- Signal to noise ratio for DEPFET telescope planes ~130, DUT module S/N ~220
- The future test system with DCD readout is also planned to use this environment





Backup Slides

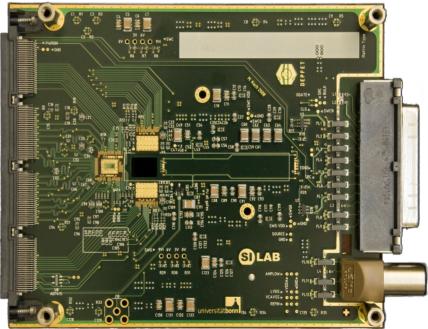


Prototype of the new R/O system



- The new prototype of ReadOut system consists of 2 PCBs:
 - → **Hybrid PCB** houses DEPFET, Steering and Readout chips
 - → Readout PCB FPGA, RAM, USB
- prototype of DCD2 chip is available (reduced number of connections) and tested on slow readout system
- DAQ for the fast readout system is based on existing USB 2.0 interface







DEPFET with EUDET Telescope



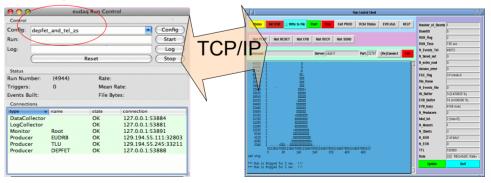
EUDET project is a program to develop the infrastructure, to facilitate the experimentation and to enable the analysis of data using shared equipment and common tools.

JRA1- test beam infrastructure (EUDET Telescope)

- 6 EUDET Modules MAPS Monolithic active pixel sensors :
 - $-7.7x7.7 \text{ mm}^2$
 - **→** 256x256 pixels
 - → pitch 30x30 µm²
- MVME6100 PowerPC computer with general purpose acquisition boards (EUDRB) inside the VME64x crate connected to 1GB ethernet HUB
- EUDET DAQ server on MAC PC, 1GB Ethernet
- Trigger Logic Unit (TLU)
- DEPFET DUT with Readout PC
- About 2 million events collected



DEPFET DUT is steered by the EUDET DAQ software

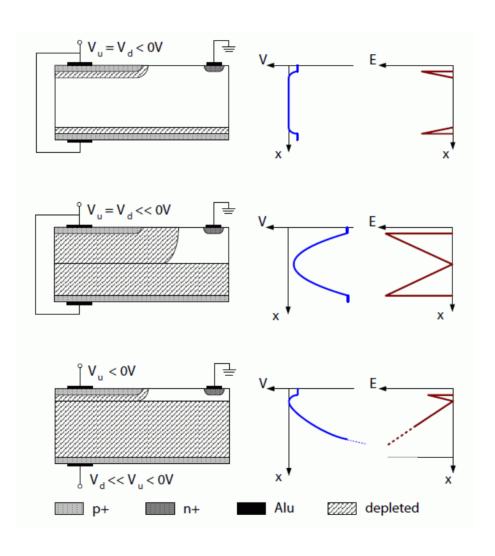


EUDET Run ControlDEPFET Run Control



DEPFET sidewards depletion

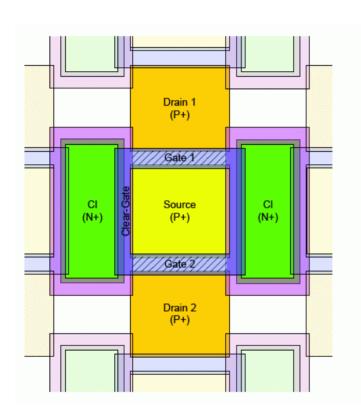


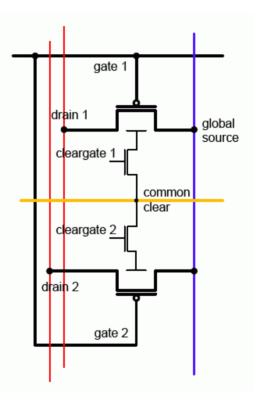




DEPFET double pixel cell



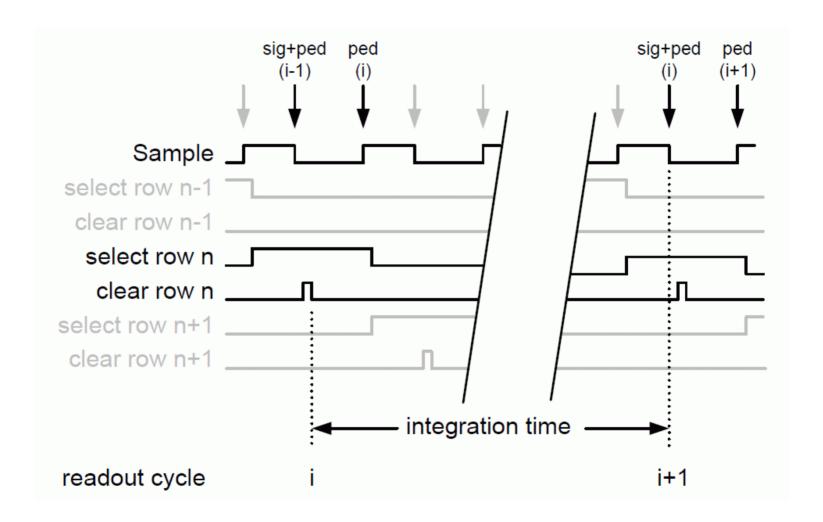






DEPFET readout sequence







The in-pixel gain



• The most probable signal is used to determine g_q :

$$g_q(nA/e-) = \frac{\mu \times 7.7(nA/ADC)}{E_{MPV}(keV)/3.6(e^-/keV)}$$

- Where:
 - μ is the most probable value in ADU:
 - The 7.7 nA/ADC corresponds to the measured gain of the CURO/S3B system
 - ightharpoonup is the most probable energy deposition in 450 μm of silicon by 120 GeV pions:
 - EMPV = 131 keV (or equivalently 36.400 e-)

The in-pixel gain of different DEPFET prototypes

sensor type, matrix & pixel size			results		
name	$row \times column$	(μm^2)	$g_q(pA/e^-)$	noise	
telescope TB2008	128×64	32×24	320 ± 20	320 ± 20	
DUT 2008	128×64	24×24	360	284	
telescope TB2009	128×128	32×24	394 ± 14	290 ± 2	
DUT CCCG	128×128	32×24	507	225	
DUT short gate	128×128	20×20	655	174	



Operation voltages of DEPFET



- Power consumption of a DEPFET matrix
- Due to the row wise addressing the power consumption does not depend on the number of rows but only on the number of columns.
- The factor 2 takes into account the splitting of the matrix into two readout directions

$$P = 2 * I_d * V_d * n_{ad} = 2 * 100 \mu A * 5V * 64 = 64 mW$$

• The power necessary to ramp up and down the gate and clear lines is mainly consumed in the Switchers

Operation	voltages of	a DEPEET	matrix with	respect to se	ource (OV)
Operation	voilages of	u DLI I'LI	man a win	respect to si	Juice (OV)

	Collection	Read	Clear		
V_{Gate}^*	3V	-2V	-2V		
V_{Clear}^*	2V	2V	15V		
V_{Drain}^{**}	-5V				
$V_{ClearGate}$	-2V				
V_{Bulk}	10V				
V_{Back}^{***}	-10V50V				

- * * control lines (transferred via Switcher)
- ** provided by readout input stage
- ★★★ depending on final detector thickness and contact mode



Network DAQ, logic view



